

# SOT599-2

plastic thin fine-pitch ball grid array package; 132 balls; body  
12 x 12 x 0.8 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	TFBGA132
<b>Package type industry code</b>	TFBGA132
<b>Package style descriptive code</b>	TFBGA (thin fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	9-1-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.8	-	12	12.2	mm
E	package width		11.8	-	12	12.2	mm
A	seated height		[tbd]	-	1.2	1.2	mm
A <sub>2</sub>	package height		0.76	-	0.8	0.84	mm
n <sub>2</sub>	actual quantity of termination		-	-	132	-	



## 2. Package outline

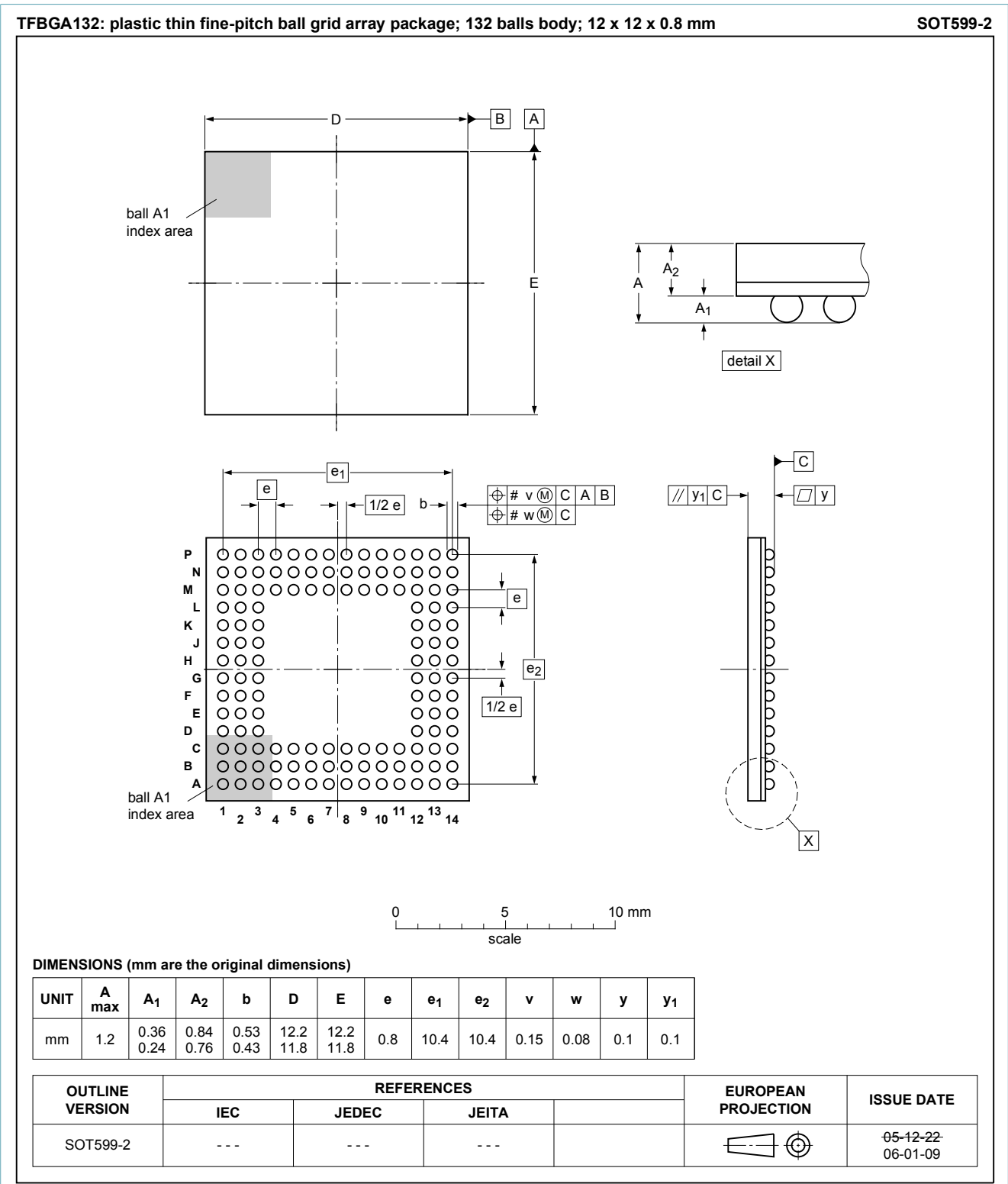


Fig. 1. Package outline TFBGA132 (SOT599-2)

3. Soldering

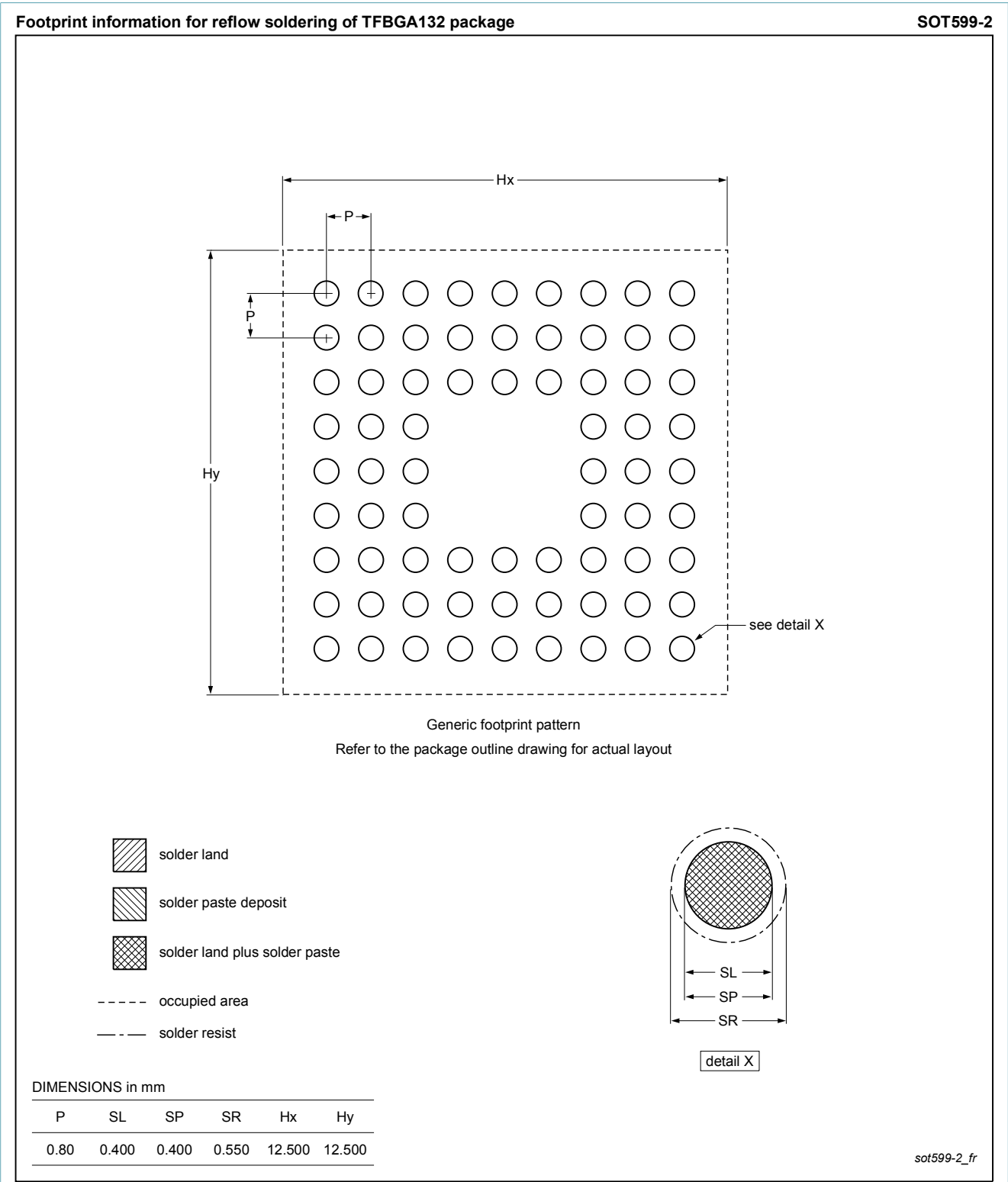


Fig. 2. Reflow soldering footprint for TFBGA132 (SOT599-2)

## 4. Legal information

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